SIEMENS

KNX EIB TP-UART 2+ - IC



Features

- Signaling for standard UART (LSB-First, Idle is 1)
- Baud rate 115200 or 19200 for the communication: TP-UART 2+ ←→ Host – Controller
- Direct coupling to host controller (TxD, RxD), or via optical couplers (optional)
- 2-wire protocol with software handshake
- Buffering of sent frames
- No critical timing during transmission
- VCC switchable between 3.3 V and 5 V
- Efficiency of VCC-supply \ge 75 %
- $I_{VCC} \le 30 \text{mA}$ (50 mA if no load at V20)
- Switchable V20 power supply 20V/25mA with limiting function
- I_{V20max} adjustable in steps
- IVB+max overshoot due to load changes actively limited
- Operating temperature range: -25°C to 85°C
- Small QFN36X36 package

GENERAL DESCRIPTION

The TP - UART - IC (Twisted Pair - Universal Asynchronous Receive Transmit - IC) is a transceiver which supports the connection of microcontrollers of sensors, actuators, or other applications to the EIB (European - Installation - Bus).

This module supports every transmit- and receive - function and also the high ohmic decoupling of energy from bus line. It generates further a stabilized 3.3V or 5V supply to use by a host controller. Up to 256 subscribers can be connected to one bus line.

An UART interface is realized for communication with a host controller. The coupling can be realized directly or via optical couplers.

The TP - UART - IC consists of two main parts: the digital part (UART - Interface) and the analog part (analog circuit part).

GENERAL DRAWING



STRUCTURE OF TP-UART 2+ - IC

(Block Diagram)



Technical Manual

TABLE OF CONTENTS

1.1 INTERFACE TO HOST ELECTRONICS .5 1.2 SELECTION OF DIFFERENT MODES OF OPERATION .5 2 THE ANALOG – PART .6 2.1 PACKAGE AND PIN DEFINITIONS .6 2.1.1 Package Pin Assignment .6 2.1.2 PIN DESCRIPTION .6 2.2 Operating conditions .8 2.1.1 General operating conditions .8 2.2.2 ABSOLUTE MAXIMUM PATINGS (NON OPERATING) .8 2.3.1 Quality Issue .10 2.4.2 Bus Pins VB+ and VB .10 2.5. CCS stabilisation Pin BYP .10 2.6. CS stabilisation Pin BYP .11 2.7.5 Supply Pin VCP .11 2.8.5 CS stabilisation Pin BYP .12 2.9 Supply Pin VDP .12 2.10 Supply Pin VDP .12 2.2.1 Supply Pin VDP .12 2.2.2 Supply Pin VDH and VSSH .22 2.11 Pus Component VDH .12 2.12 Pin SVDC .15 2.13	1 MODES OF OPERATION	5
12 SELECTION OF DIFFERENT MODES OF OPERATION 5 2 THE ANALOG – PART 6 2.1 PACKAGE AND PIN DEFINITIONS 6 2.1.1 Package Pin Assignment 6 2.1.2 PIN DESCRIPTION 6 2.2 OPERATING CONDITIONS 8 2.1 General operating conditions 8 2.2.1 General operating conditions 8 2.2.2 ABSOLUTE MAXIMUM RATINGS (NON OPERATING) 8 2.2.3 Cuality Issue 10 2.2.4 Bus Pins VB+ and VB- 10 2.2.5 CCS stabilisation Pin BYP 10 2.2.6 Duffer Voltage Pin VSP 11 2.2.7 Supply Pin VCC 11 2.2.8 Supply Pin VCC 11 2.2.9 Supply Pin VDH and VSSH 12 2.2.10 Supply Pin VCC 13 2.2.11 Pin IND, SMPS-output 14 2.2.12 Pin SVCC 15 2.2.13 Supply Pin VIP 15 2.2.14 Transmit Pin TxO 15 2.2.15 Supply Pin VIP<	1.1 INTERFACE TO HOST ELECTRONICS	5
2 THE ANALOG - PART 6 2.1 PACKAGE AND PIN DEFINITIONS 6 2.1.1 Package Pin Assignment 6 2.1.2 PIN DESCRIPTION 6 2.1 2 PIN DESCRIPTION 6 2.2 OPERATING CONDITIONS 8 2.1.2 LIN DESCRIPTION 8 2.2.1 General operating conditions 8 2.2.2 ABSOLUTE MAXIMUM RATINGS (NON OPERATING) 8 2.2.3 Quity Issue 10 2.2.4 Bus Pins VB+ and VB- 10 2.2.5 CCS stabilisation Pin BYP 10 2.2.6 Buffer Voltage Pin VSP 11 2.2.7 Supply Pin VCC 11 2.2.8 Supply Pin VCC 11 2.2.9 Supply Pin VCC 12 2.10 Supply Pin VCC 13 2.2.10 Supply Pin VCC 13 2.2.10 Supply Pin VCC 15 2.2.13 Supply Pin VCC 15 2.2.14 Transmit Pin TxO 15 2.2.15 Supply Pin VIF 15 2.2.16 Supply Pin VIF 15 2.2.15 Supply Pin VIF 15 2.2.16 Supply Pin VIF 15 2.2.17 In I	1.2 SELECTION OF DIFFERENT MODES OF OPERATION	
2 THE ANALOG – PART		
2.1 PACKAGE AND PIN DEFINITIONS 6 2.1.1 Package Pin Assignment 6 2.1.2 PIN DESCRIPTION 6 2.1.2 PIN DESCRIPTION 6 2.1.2 PIN DESCRIPTION 6 2.1.2 PIN DESCRIPTION 6 2.2.1 General operating conditions 8 2.2.3 ABSOLUTE MAXIMUM RATINGS (NON OPERATING) 8 2.2.3 Quality Issue. 10 2.4.5 ECS stabilisation Pin BYP 10 2.5.4 CCS stabilisation Pin BYP 10 2.6.6 Buffer Voltage Pin VSP 11 2.7.5 Supply Pin VDP 12 2.8.5 Supply Pin VDP 12 2.9.5 Supply Pin VDP 12 2.10 Supply Vin VDH and VSSH 12 2.2.10 Supply Pin VDD 13 2.2.11 Pin ND, SMPS-output 14 2.2.2.5 Supply Pin VIF 15 2.2.13 Receive Pin RxIN 15 2.2.14 Transmit Pin TxO 15 2.2.15 Supply Pin VIF 15	2 THE ANALOG – PART	6
21.1 Package Pin Assignment 6 21.2 PIN DESCRIPTION 6 2.1 PerRATING CONDITIONS 8 2.2.1 General operating conditions 8 2.2.1 General operating conditions 8 2.2.2 ABSOLUTE MAXIMUM RATINGS (NON OPERATING) 8 2.2.3 Quality Issue 10 2.2.4 Bus Pins VB+ and VB- 10 2.2.5 CS stabilisation Pin BYP 10 2.2.6 Supply Pin VDP 11 2.2.7 Supply Pin VDP 11 2.2.8 Supply Pin VDP 12 2.2.9 Supply Pin VDP 12 2.2.10 Supply Pin VDD and VSSH 12 2.2.10 Supply Pin VD2 and Pin R20 13 2.2.11 Pin NDS.Supply Pin VD2 13 2.2.12 Supply Pin VCC 15 2.13 Receive Pin RxIN 15 2.2.14 transmit Pin TXO 15 2.2.15 Supply Pin VF 15 2.2.16 Oscillator Pins X1 and X2 15 2.2.17 Interface Pin TXD	2.1 PACKAGE AND PIN DEFINITIONS	6
21.2 PIN DESCRIPTION 6 22 OPERATING CONDITIONS 8 22.1 General operating conditions 8 22.2 ABSOLUTE MAXIMUM RATINGS (NON OPERATING) 8 22.2 ABSOLUTE MAXIMUM RATINGS (NON OPERATING) 8 22.4 Bus Pins VB+ and VB- 10 2.5 CCS stabilisation Pin BYP 10 2.6 Buffer Voltage Pin VSP. 11 2.7 Supply Pin VCC 11 2.8 Supply Pin VDP. 12 2.9 Supply Pin VDP and VSSH 12 2.10 Supply Pin VD and PIN R20 13 2.2.11 Pin VDD and VSSH 12 2.2.10 Supply Pin VCC 13 2.2.11 Pin ND, SMPS-output 14 2.2.12 Supply Pin VIC 15 2.13 Receive Pin RxIN 15 2.2.14 transmit Pin TXO 15 2.2.15 Supply Pin VIF 15 2.2.16 Oscillator Pin SX1 and X2 15 2.2.17 Interface Pin RxD 16 2.2.18 Interface Pin RxD	2.1.1 Package Pin Assignment	6
2.2 OPERATING CONDITIONS	2.1.2 PIN DESCRIPTION	6
22.1 General operating conditions 8 22.2 ABSOLUTE MAXIMUM RATINGS (NON OPERATING) 8 2.3 Quality Issue 10 2.4 Bus Pins VB+ and VB- 10 2.2.4 Bus Pins VB+ and VB- 10 2.2.5 CS stabilisation Pin BYP 10 2.2.6 Buffer Voltage Pin VSP 11 2.2.7 Supply Pin VCC 11 2.2.8 Supply Pin VDP 12 2.2.9 Supply Pins VDDH and VSSH 12 2.2.10 Supply Pins VDD and VSSH 12 2.2.10 Supply Pins VDC 13 2.2.11 Pin ND, SMPS-output 14 2.2.12 Supply Pin VIC 15 2.13 Receive Pin RxIN 15 2.2.14 Transmit Pin TxO 15 2.2.15 Supply Pin VIF 15 2.2.16 Oscillator Pins X1 and X2 15 2.2.17 Interface Pin RxD 16 2.2.19 Switching Pin STxO 16 2.2.19 Switching Pin STxO 16 2.2.20 Reset Pin RESn	2.2 OPERATING CONDITIONS	8
222 ABSOLUTE MAXIMUM RATINGS (NON OPERATING) 8 223 Quality Issue 10 224 Bus Pins VB+ and VB- 10 225 CCS stabilisation Pin BYP 10 226 Buffer Voltage Pin VSP 11 227 Supply Pin VCC 11 228 Supply Pin VDP 12 229 Supply Pin VDDH and VSSH 12 2210 Supply Pin VDD and Pin R20 13 22.11 Pin ND, SMPS-output 14 22.12 Supply Pin V20 and Pin R20 15 22.13 Receive Pin RxIN 15 22.14 Transmit Pin TxO 15 22.15 Supply Pin VIF 15 22.16 Oscillator Pins X1 and X2 15 22.17 Interface Pin RxD 16 22.18 Interface Pin TxD 16 22.19 Switching Pin STxO 16 22.21 Node control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 22.22 Pin TSTIN_BDS 18 22.23 Pin TSTW 18 22.24 Pin SAVE </td <td>2.2.1 General operating conditions</td> <td>8</td>	2.2.1 General operating conditions	8
22.3 Quality Issue. 10 22.4 Bus Pins VB- and VB- 10 22.5 CCS stabilisation Pin BYP 10 22.6 Buffer Voltage Pin VSP 11 22.7 Supply Pin VCC 11 22.8 Supply Pin VCC 11 22.9 Supply Pin VDP 12 22.10 Supply Pin VDD and VSSH 12 22.11 Pin IND, SMPS-output 14 22.12 Supply Pin V20 and Pin R20 13 22.11 Pin IND, SMPS-output 14 22.12 Supply Pin VIP 15 22.13 Receive Pin RxIN 15 22.14 Transmit Pin TxO 15 22.15 Supply Pin VIF 15 22.16 Oscillator Pins X1 and X2 15 22.17 Interface Pin RxD 16 22.19 Switching Pin STxO 16 22.20 Reset Pin RESn 17 22.21 Pin TSTN_BDS 18 22.22 Pin TSTN_BDS 18 22.22 Pin TSTN_BDS 18 22.22	2.2.2 ABSOLUTE MAXIMUM RATINGS (NON OPERATING)	8
22.4 Bus Pins VB+ and VB	2.2.3 Quality Issue	10
22.5 CCS stabilisation Pin BYP. 10 22.6 Buffer Voltage Pin VSP. 11 22.7 Supply Pin VCC 11 22.8 Supply Pin VDP. 12 22.9 Supply Pins VDDH and VSSH 12 22.10 Supply Pins VDD and VSSH 12 22.11 Pin SVCC 13 22.11 Pin SVCC 15 22.13 Receive Pin RxIN 15 22.14 Transmit Pin TxO 15 22.15 Supply Pin VIF 15 22.16 Oscillator Pins X1 and X2 15 22.17 Interface Pin RxD 16 22.18 Supply Pin STxO 16 22.19 Switching Pin STxO 16 22.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 22.22 Pin TSTOUT_TW 18 22.24 Pin SAVE 19 2.225 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21<	2.2.4 Bus Pins VB+ and VB	10
22.6 Buffer Voltage Pin VSP. 11 22.7 Supply Pin VCC 11 22.8 Supply Pin VDP. 12 22.9 Supply Pins VDH and VSSH 12 22.10 Supply Pin V20 and Pin R20 13 22.11 Pin IND, SMPS-output 14 22.12 Pin SVCC 15 22.13 Receive Pin RxIN 15 22.14 Transmit Pin TxO 15 22.15 Supply Pin VIF 15 22.16 Oscillator Pins X1 and X2 15 22.17 Interface Pin TxD 16 22.19 Switching Pin STxO 16 22.20 Reset Pin RESn 17 22.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 22.22 Pin TSTOUT_TW 18 22.23 Pin SAVE 19 22.24 Pin SAVE 19 22.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21	2.2.5 CCS stabilisation Pin BYP	10
22.7 Supply Pin VCC 11 22.8 Supply Pins VDDH and VSSH 12 22.9 Supply Pins VDDH and VSSH 12 22.10 Supply Pin V20 and Pin R20 13 22.11 Pin IND, SMPS-output 14 22.12 Pin SVCC 15 22.13 Receive Pin RxIN 15 22.14 Transmit Pin TxO 15 22.15 Supply Pin VIF 15 22.16 Oscillator Pins X1 and X2 15 22.17 Interface Pin RxD 16 22.18 Interface Pin TxD 16 22.19 Switching Pin STXO 16 22.10 Reset Pin RESn 17 2.22 Reset Pin RESn 17 2.22.11 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 2.22.21 Pin TSTIN_BDS 18 2.22.23 Pin TSTOUT_TW 18 2.22.24 Pin SAVE 19 2.22.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20	2.2.6 Buffer Voltage Pin VSP	11
22.8 Supply Pin VDP. 12 22.9 Supply Pin VDD and VSSH 12 22.10 Supply Pin V20 and Pin R20. 13 22.11 Pin IND, SMPS-output 14 22.12 Pin SVCC 15 22.13 Receive Pin RxIN. 15 22.14 Transmit Pin TxO 15 22.15 Supply Pin VIF 15 22.16 Oscillator Pins X1 and X2 15 22.17 Interface Pin RxD 16 22.18 Interface Pin TxD 16 22.19 Switching Pin STxO 16 22.20 Reset Pin RESn 17 22.21 Pin STIN_BDS 18 22.22 Pin TSTOUT_TW 18 22.23 Pin TSTOUT_TW 18 22.24 Pin SAVE 19 22.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART - INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 <td>2.2.7 Supply Pin VCC</td> <td>11</td>	2.2.7 Supply Pin VCC	11
22.9 Supply Pins VDDH and VSSH 12 22.10 Supply Pin V20 and Pin R20 13 22.11 Pin IND, SMPS-output 14 22.12 Pin SVCC 15 22.13 Receive Pin RxIN 15 22.14 Transmit Pin TxO 15 22.15 Supply Pin VIF 15 22.16 Oscillator Pins X1 and X2 15 22.17 Interface Pin RxD 16 22.18 Interface Pin TxD 16 22.19 Switching Pin STxO 16 22.20 Reset Pin RESn 17 22.21 Pin TSTIN_BDS 18 22.22 Pin TSTIN_BDS 18 22.23 Pin TSTOUT_TW 18 22.24 Pin SAVE 19 22.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART - INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 <tr< td=""><td>2.2.8 Supply Pin VDP</td><td></td></tr<>	2.2.8 Supply Pin VDP	
2.2.10 Supply Pin V20 and Pin R20 13 2.2.11 Pin IND, SMPS-output 14 2.2.12 Pin SVCC 15 2.2.13 Receive Pin RxIN 15 2.2.14 Transmit Pin TxO 15 2.2.15 Supply Pin VIF 15 2.2.16 Oscillator Pins X1 and X2 15 2.2.17 Interface Pin RxD 16 2.2.18 Interface Pin TxD 16 2.2.19 Switching Pin STxO 16 2.2.20 Reset Pin RESn 17 2.2.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 2.2.22 Pin TSTIN_BDS 18 2.2.23 Pin TSTOUT_TW 18 2.2.24 Pin SAVE 19 2.2.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	2.2.9 Supply Pins VDDH and VSSH	
2.2.11 Pin IND, SMIPS-Output 14 2.2.12 Pin SVCC 15 2.2.13 Receive Pin RxIN 15 2.2.14 Transmit Pin TxO 15 2.2.15 Supply Pin VIF 15 2.2.16 Oscillator Pins X1 and X2 15 2.2.17 Interface Pin RxD 16 2.2.18 Interface Pin TxD 16 2.2.19 Switching Pin STxO 16 2.2.20 Reset Pin RESn 17 2.2.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 2.2.22 Pin TSTIN_BDS 18 2.2.23 Pin TSTOUT_TW 18 2.2.24 Pin SAVE 19 2.2.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	2.2.10 Supply Pin V20 and Pin R20	
2.2.12 Pin SVCC 15 2.2.13 Receive Pin RxIN 15 2.2.14 Transmit Pin TxO 15 2.2.15 Supply Pin VIF 15 2.2.16 Oscillator Pins X1 and X2 15 2.2.17 Interface Pin RxD 16 2.2.18 Interface Pin TxD 16 2.2.19 Switching Pin STxO 16 2.2.20 Reset Pin RESn 17 2.2.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 2.2.22 Pin TSTIN_BDS 18 2.2.23 Pin TSTOUT_TW 18 2.2.24 Pin SAVE 19 2.2.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21		
2.2.13 Receive FIT TXN 15 2.2.14 Transmit Pin TxO 15 2.2.15 Supply Pin VIF 15 2.2.16 Oscillator Pins X1 and X2 15 2.2.17 Interface Pin RxD 16 2.2.18 Interface Pin TxD 16 2.2.19 Switching Pin STxO 16 2.2.19 Switching Pin STxO 16 2.2.20 Reset Pin RESn 17 2.2.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 2.2.22 Pin TSTIN_BDS 18 2.2.23 Pin TSTOUT_TW 18 2.2.24 Pin SAVE 19 2.2.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	2.2.12 PIII SVUU	15 15
2.2.15 Supply Pin VIF 15 2.2.15 Supply Pin VIF 15 2.2.16 Oscillator Pins X1 and X2 15 2.2.17 Interface Pin RxD 16 2.2.18 Interface Pin TxD 16 2.2.19 Switching Pin STxO 16 2.2.20 Reset Pin RESn 17 2.2.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 2.2.22 Pin TSTIN_BDS 18 2.2.23 Pin TSTOUT_TW 18 2.2.24 Pin SAVE 19 2.2.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	2.2.13 RECEIVE FILL RAIN	
2.2.16 Oscillator Pins X1 and X2 15 2.2.17 Interface Pin RxD 16 2.2.18 Interface Pin TxD 16 2.2.19 Switching Pin STxO 16 2.2.20 Reset Pin RESn 16 2.2.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 2.2.22 Pin TSTIN_BDS 18 2.2.23 Pin TSTOUT_TW 18 2.2.24 Pin SAVE 19 2.2.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.3 UART-Protocol Definition 21	2.2.14 Transmitt in TXO	
2.2.17 Interface Pin RxD 16 2.2.18 Interface Pin TxD 16 2.2.19 Switching Pin STxO 16 2.2.20 Reset Pin RESn 17 2.2.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 2.2.22 Pin TSTIN_BDS 18 2.2.23 Pin TSTOUT_TW 18 2.2.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	2.2.16 Oscillator Pins X1 and X2	
2.2.18 Interface Pin TxD 16 2.2.19 Switching Pin STxO 16 2.2.20 Reset Pin RESn 17 2.2.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 2.2.22 Pin TSTIN_BDS 18 2.2.23 Pin TSTOUT_TW 18 2.2.25 Pin DIV 19 2.2.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	2.2.17 Interface Pin RxD	
2.2.19 Switching Pin STxO 16 2.2.20 Reset Pin RESn 17 2.2.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 2.2.22 Pin TSTIN_BDS 18 2.2.23 Pin TSTOUT_TW 18 2.2.24 Pin SAVE 19 2.2.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	2.2.18 Interface Pin TxD	
2.2.20 Reset Pin RESn 17 2.2.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM 17 2.2.22 Pin TSTIN_BDS 18 2.2.23 Pin TSTOUT_TW 18 2.2.24 Pin SAVE 19 2.2.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	2.2.19 Switching Pin STxO	
2.2.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM. 17 2.2.22 Pin TSTIN_BDS 18 2.2.23 Pin TSTOUT_TW. 18 2.2.24 Pin SAVE. 19 2.2.25 Pin DIV. 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER. 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	2.2.20 Reset Pin RESn	17
2.2.22 Pin TSTIN_BDS 18 2.2.23 Pin TSTOUT_TW 18 2.2.24 Pin SAVE 19 2.2.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	2.2.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM	17
2.2.23 Pin TSTOUT_TW	2.2.22 Pin TSTIN_BDS	18
2.2.24 Pin SAVE 19 2.2.25 Pin DIV 19 3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	2.2.23 Pin TSTOUT_TW	18
2.2.25 Pin DIV	2.2.24 Pin SAVE	19
3 DIGITALPART 20 3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	2.2.25 Pin DIV	19
3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL 20 3.2 UART – INTERFACE TO HOST CONTROLLER 21 3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	3 DIGITALPART	20
3.2 UART – INTERFACE TO HOST CONTROLLER. 21 3.2.1 Configuration and Timing	3.1 RELATIONSHIP TO ISO-REFERENCE-MODEL	20
3.2.1 Configuration and Timing 21 3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	3.2 UART – INTERFACE TO HOST CONTROLLER	21
3.2.2 Resetbehavior 21 3.2.3 UART-Protocol Definition 21	321 Configuration and Timing	21
3.2.3 UART-Protocol Definition	3.2.2 Resetbehavior	
	3.2.3 UART-Protocol Definition	21

pages 43

Technical Manual

4 MECHANICAL SPECIFICATION	35
4.1 PACKAGE	
5 TAPE AND REEL PACKING	
6 SOLDERING PROFILE	
7 APPENDIX	40
7.1 TYPICAL APPLICATION CIRCUITS	40
7.1.1 Mode of Operation – Normal	40
7.1.2 Mode of Operation – Analog	41
7.2 LAYOUT GUIDELINES	41

page 4

1 Modes of Operation

1.1 Interface to host electronics



1.2 Selection of Different Modes of Operation

Mode of operation	MODE		TEST MODE	СТМ	TSTIN_BDS	TSTOUT_TW		
	0	1	2	3				
Normal	1	1	0	0	0	0	BDS=0: 19.2 kBd at UART BDS=1: 115.2 KBd at UART	TW
Analog	1	0	0	0	0	0	0	TW

Table 1: Modes of Operation

2 The ANALOG – PART

2.1 Package and Pin Definitions

2.1.1 Package Pin Assignment



Figure 1 Package Pin Assignment

2.1.2 PIN DESCRIPTION

Pin	Pin Name	Pin Type	Positive supply	Negative supply	Notes
1	NC0	AIO	VB+	VB-	Used during chip test mode
2	R20	AIO	VDP	VB-	External resistor to VB- sets V20 max current
3	V20	AIO	50V Clamp to VB-	VB-	Internally generated 20V power supply
4	VSP	AIO	50V Clamp to VB-	VB-	Intermediate voltage blocking capacitor
5	VSSH	AIO	VSP	VB-	SMPS control

Technical Manual

pages 43

6	VDDH	AIO	VSP	VB-	SMPS control
7	SVCC	AIO	VCC	VB-	VCC control
8	VCC	AIO	5.5V Clamp to VB-	VB-	External power supply 3.3/5 V
9	IND	AIO	VSP	VB-	SMPS-output; no external freewheeling diode
10	VB-	S	Gro	bund	Negative bus pin, exposed pad (see Figure 5 and 7.2 Layout Guidelines)
11	VB+	S	70V Clamp to VB-	VB-	Positive bus pin
12	BYP	AIO	VB+	VB-	Bypass current stabilisation pin
13	ТХО	AIO	VB+	VB-	Transmit output current (bus signal)
14	STxO	AIO	VB+	VB-	Transmitting active indication
15	RxIN	AIO	VB+	VB-	Capacitive coupled to bus signal
16	VB-	S	Ground	Negative bus pin	
17	VIF	S	5.5V Clamp to VB-	VB-	External supply for IO cells
18	SAVE	DO_PU	VIF	VB-	Signalization of bus voltage break-down
19	RESn	DIO_PU	VIF	VB-	Reset pin, open drain with internal pullup
20	RxD	DI_PD	VIF	VB-	Data receive from host with internal pulldown
21	TxD	DO	VIF	VB-	Data transmission to host
22	TSTOUT_TW	DO	VIF	VB-	Digital test / temperature signal
23	X1	DI	VIF	VB-	Crystal oscillator pin 1; external clock input
24	X2	DO	VIF	VB-	Crystal oscillator pin 2
25	V20PD	DI	VDP	VB-	Enable and disable V20
26	NC2	DIO	VDP	VB-	Used during chip test mode
27	NC3	AIO	VDP	NA	
28	VDP	AIO	5.5V Clamp to VB-	VB-	Storage capacitor for internal power supply
29	TSTIN_BDS	DIO	VDP	VB-	Input for digital test / baud rate select; digital output for analog test
30	DIV	DI	VDP	VB-	Internal clock divider 2:1 active
31	CTM_AMS	DI	VDP	VB-	Chip Test mode control
32	MODE 3	DI	VDP	VB-	Chip Test Mode control pin 4
33	MODE 2	DI	VDP	VB-	Chip Test Mode / Mode control pin 3
34	MODE 1	DI	VDP	VB-	Mode control pin 2
35	MODE 0	DI	VDP	VB-	Mode control pin 1
36	TESTMODE	DI	VDP	VB-	Test mode control

Table 2: Pin Description

PIN Types:

supply pad

... analog I/O

...

... digital input

DI_PU ... digital input with pull-up

S

AIO

DI

 digital input with pull-down
 digital I/O with pull-up
 digital output
 digital output with pull-up
 Not connected. Recommend to be tied to VB- in the application.

2.2 OPERATING CONDITIONS

2.2.1 General operating conditions

All specification parameters, unless otherwise stated, are valid within the General operating conditions. Unless otherwise stated all voltages are referenced to the VB- pin.

Symbol	Parameter	Min	Max	Unit	Note			
VB+	positive line voltage	11	45	V	1)			
V _{cc}	positive supply voltage for external supply	5.0 - 5%	5.0 + 5%	V	2)			
	(digital test modes with SHB = 0)	3.3 - 5%	3.3 + 5%	V	2)			
V _{IF}	positive external supply voltage	3.0	5.5	V				
T _{amb}	ambient temperature	-25	85	°C				
T _{inc1}	Junction temperature		125	°C				
f _{clk} clock frequency (external quartz)			4.9152	MHz	3)			
1) DC voltage of bus is 20V to 30V, with signal and compensation pulse 11 V 45 V								
2) set by SVCC								
3) 4.9	915MHz external clock running							

Table 3 General operating conditions

2.2.2 ABSOLUTE MAXIMUM RATINGS (NON OPERATING)

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated under "Operating Conditions" is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Unless otherwise stated all voltages are referenced to the VB- pin.

Parameter	Symbol	Min	Max	Unit	Note
positive line voltage	VB+	-0.3	50	V	1)
positive supply voltage (internal or external supply)	V _{CC}	-0.3	7	V	2)
positive external supply voltage	V_{IF}	-0.3	7	V	2)
intermediate voltage (generated by on-chip regulator)	V_{VSP}	-0.3	50	V	2)
voltage on pin TxO	V _{TxO}	-0.3	50	V	1)
voltage on pin RxIN	V_{RxIN}	-0.3	50	V	1), 4)
voltage on pin BYP	V_{BYP}	-0.3	50	V	1)
voltage on pin STxO	V _{STxO}	-0.3	50	V	1)

Technical Manual

pages 43

Parameter	Symbol	Min	Max	Unit	Note
voltage on pin V20	V ₂₀	-0.3	25	V	2)
voltage on pin IND	V _{IND}	-0.3	50	V	
voltage on low voltage pins MODE0, MODE1, MODE2, MODE3, TSTIN_BDS, TESTMODE, DIV, SVCC, CTM	V _{LV1}	-0.3	V _{DP} +0.5	V	9)
voltage on low voltage pins TxD, RESn, TSTOUT_TW, X1, X2, RxD, SAVE	V _{LV2}	-0.3	V _{IF} +0.5	V	5)
Internal supply voltage to digital part	V _{VDP}	-0.3	5	V	
voltage used for internal DC/DC- converter	V _{VDDH}	-0.3	50	V	
voltage used for internal DC/DC- converter	V _{VSSH}	-0.3	50	V	
Ambient temperature	T _{amb}	-25	85	°C	
Junction temperature	Tj		145	°C	
storage temperature	Ts	-65	150	°C	
ESD stress voltage that will not cause damage to the device	V _{ESD}		± 1200	V	3)
static current for latchup initialization	ILATCHUP	± 50		mA	
thermal resistance of QFN package to ambient	R _{tha}		28	K/W	6)
thermal resistance of QFN package to package surface measured on exposed paddle	R _{ths}		5	K/W	6)
Total power dissipation at T_{amb} = 85° C (all supplies and outputs)	Pt		1.4	W	TW not active 7)
Humidity non-condensing	H _{NC}	5	93	%	8)

Table 4 Absolute maximum ratings

Notes:

- (1) during surge impulse: -20 V for 2 μ sec and +65 V for 150 μ sec
- (2) In particular allowed voltage relations (no damage under following voltage relations):
 - (a) $V_{VSP} \ge VB+$; e.g. VB+ = 0 V due to a short circuit
 - (b) $V_{V20} \ge V_{VSP}$; e.g. V_{VSP} = 0 V due to a short circuit or VB+ = 0 V
 - (c) $V_{VCC} \ge V_{VSP}$; e.g. V_{VSP} = 0 V due to a short circuit or VB+ = 0 V
 - (d) $V_{IF} \ge V_{VCC}$; e.g. when an external supply for V_{IF} is used and VB+ = 0 V
 - (e) V_{CC} and V_{VSP} normal / VB+ and V_{IF} can be 0 V
 - (f) $V_{\text{VSP}}\,\text{normal}$ / V_{CC} , VB+ and $V_{\text{IF}}\,\text{can be 0}\,\text{V}$
 - (g) V_{IF} normal / V_{CC} , VB+ and V_{VSP} can be 0 V
 - (h) $V_{DP} \ge V_{VSP}$; e.g during normal startup sequence.
- (3) human body model: 100 pF, $1.5 \text{ k}\Omega$, Mil. Std. 883, method 3015.7
- (4) dynamic via C_{REC}= 47 nF in case of switching-on/off the bus voltage, complies with V_{CREC} at normal operation, may be down to -20 V.

- (5) max. 7 V
- (6) Measurement conditions in accordance with EIA/JEDEC STANDARD 51-2. Value is an estimate only.
- (7) For $R_{th} \leq 28k/W$
- (8) Valid susceptibility against humidity is described by JEDEC JESD22-A112, table 1, level 5
- (9) Max. 5V

2.2.3 Quality Issue

60 FIT at 70 °C

2.2.4 Bus Pins VB+ and VB-

Via these pins the ASIC is connected to the bus lines. External diode to prevent reverse bias of ASIC and external suppressor diode to limit the burst pulses are required.

Parameter	Min	Max	Unit	Note		
positive line voltage		45	V	1)		
I _{analog} current consumption in analog mode (without		1	mA	2) 4)		
external clock)						
urrent consumption in normal mode (with external		2.1	mA	3) 4)		
lock)						
I _{analog} current consumption in analog mode (without		1	mA	2) 5)		
external clock)						
urrent consumption in normal mode (with external		2.1	mA	3) 5)		
lock)						
voltage of bus is 20V to 30V. During surge impulse:	-20 V for 2	2 µs and	65 V fo	r 150 µs		
bad at all (VCC, V20, I/O-pins)						
3) 4.915MHz external clock running						
4) SVCC connected to VCC (nominal VCC = 5V)						
C connected to VB- (nominal VCC = 3.3V)						
	ositive line voltage urrent consumption in analog mode (without xternal clock) urrent consumption in normal mode (with external lock) urrent consumption in analog mode (without xternal clock) urrent consumption in normal mode (with external lock) roltage of bus is 20V to 30V. During surge impulse: bad at all (VCC, V20, I/O-pins) 5MHz external clock running C connected to VCC (nominal VCC = 5V) C connected to VB- (nominal VCC = 3.3V)	ositive line voltage -0.3 urrent consumption in analog mode (without xternal clock) -0.3 urrent consumption in normal mode (with external lock) -0.3 urrent consumption in normal mode (with external lock) -0.3 urrent consumption in analog mode (with external lock) -0.3 urrent consumption in normal mode (with external lock) -0.3 urrent consumption in normal mode (with external lock) -0.3 voltage of bus is 20V to 30V. During surge impulse: -20 V for 2 bad at all (VCC, V20, I/O-pins) -0.3 5MHz external clock running C connected to VCC (nominal VCC = 5V) C connected to VB- (nominal VCC = 3.3V) -0.3	ositive line voltage -0.3 45 urrent consumption in analog mode (without 1 xternal clock) 2.1 lock) 2.1 urrent consumption in normal mode (with external 2.1 lock) 1 urrent consumption in analog mode (without 1 vertext consumption in analog mode (with external 2.1 lock) 2.1 urrent consumption in normal mode (with external 2.1 lock) 2.1 voltage of bus is 20V to 30V. During surge impulse: -20 V for 2 µs and bad at all (VCC, V20, I/O-pins) 5MHz external clock running C connected to VCC (nominal VCC = 5V) C connected to VB- (nominal VCC = 3.3V)	ositive line voltage -0.3 45 V urrent consumption in analog mode (without 1 mA xternal clock) urrent consumption in normal mode (with external 2.1 mA lock) urrent consumption in analog mode (without 1 mA urrent consumption in analog mode (without 1 mA lock) urrent consumption in analog mode (without 1 mA urrent consumption in normal mode (with external 2.1 mA lock) urrent consumption in normal mode (with external 2.1 mA lock) voltage of bus is 20V to 30V. During surge impulse: -20 V for 2 µs and 65 V for a at all (VCC, V20, I/O-pins) 55MHz external clock running C connected to VCC (nominal VCC = 5V) C connected to VB- (nominal VCC = 3.3V) 1000000000000000000000000000000000000		

Table 5 Bus Pins VB+ and VB-

2.2.5 CCS stabilisation Pin BYP

The BYP pin drives the control node of the controlled current source (CCS) via a capacitor connected to the VB+ bus line. This drive is used to ensure that the capacitive loading on the EIB, by the ASIC, is below a specific value.

Symbol	Parameter	Min	Max	Unit	Note	
V _{BYP}	Bypass voltage range	-0.3	45	V	1)	
C _{BYP}	external coupling capacitance	44.5	49.5	nF	typ. 47 nF	
1) DC voltage of bus is 20V to 30V. During surge impulse: -20 V for 2 μs and 65 V for 150 μs						
Table C 000 stabilisetism via DVD						

Table 6 CCS stabilisation pin BYP

Technical I	Manual
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pages 43

2.2.6 Buffer Voltage Pin VSP

The ASIC delivers a supply voltage of 3.3 or 5 volts to external loads. In order to prevent a rapid change of bus current in the case of a rapid change of external load an external capacitor at the pin VSP is used for energy storage. The static voltage at VSP is adjusted to V_{VB+} - V_{VDIF} . V_{VSP} is connected by a short circuit to pin VDDH externally in the application. VDDH is used as the input for the VCC DC-DC converter and the VSSH regulator. VSP is used as the input for V20 linear regulator and VDP linear regulator.

Symbol	Parameter	Min	Max	Unit	Note
V _{VSP}	energy buffer voltage	V_{VB+} - V_{VDIF}	30	V	1)
V _{VDIF}	voltage difference between V_{VB+} and V_{VSP}	0.5	2	V	
C _{VSP}	external storage capacitance	120		μF	2) 6)7)
ESR _{VSP1}	ESR of external storage capacitance evaluated @		0.70	Ω	8)
ESR _{VSP2}	ESR of external storage capacitance evaluated @ 100kz		0.20	Ω	8)

1) DC voltage of bus is 20V to 30V.

2) recommended 330 μ F; must be larger than the capacitor at VCC

6) It is highly recommended, but not mandatory, that an additional capacitor C_{VDDH} is included in any application configuration where capacitors C_{VSP} is present. When present it is recommended that C_{VDDH} be placed as close as possible to pin VDDH.

7) C_{VSP} affects the max. allowed load current at VCC and V20 (see 2.2.7 and 2.2.10).

If $C_{VSP} < 330 \ \mu F \pm 20\%$ fan in has to be multiplied by $264 \mu F/C_{VSP}$.

There are no restrictions if $C_{VSP} \ge 264 \ \mu F$ (Therefore 330 $\mu F \pm 20 \ \%$ is recommended.).

8) If C_{VSP} < 330 µF ±20% ESR has to be multiplied by 264µF/C_{VSP}.



Table 7 Buffer Voltage Pin VSP

Figure 2 VCC supply external connections

2.2.7 Supply Pin VCC

Pin VCC delivers the internally generated supply voltage to external loads. The supply is generated by a switched mode power supply (with an internal oscillator, softstart function), current source and shunt regulator. The voltage of VCC depends on the level of pin SVCC. Internal input voltage for VCC (switched mode power supply) is VDDH. VCC supply generation is disabled during softstart.

The I_{VCC} maximum current can be greater than 30mA if the maximum I_{V20} current is reduced.

Symbol	Parameter	Min	Max	Unit	Note			
V _{IN}	input voltage	6.25	33	V				
V _{VCC[5]}	supply voltage (generated by the ASIC)	5.0-5%	5.0+5%	V	1)			
V _{VCC[3]}	supply voltage (generated by the ASIC)	3.3-5%	3.3+5%	V	2)			
C _{VCC}	external storage capacitance	8	18	μF				
L _{VCC}	External Inductance	22	0	μH				
L _{VCC}	External Inductor	Series loss	resistance		3)4)			
		≤ 7.5	5Ω					
C _{VCCESR}	ESR of external storage and load capacitance to	0.3	0.7	Ω				
	achieve V _{ripple1}							
I _{VCC}	external load at VCC	0	30	mA	5)			
	with reduced I _{V20}		50	mA	5)			
1) SV	CC connected to VCC							
2) SV	2) SVCC connected to VB-							

- 3) Such as EPCOS SIMID B824432C part No. B824321224K000
- 4) If series loss resistance $\leq 1 \Omega$ an efficiency of typical 80 % will be reached

5) If $C_{VSP} < 330 \ \mu\text{F} \pm 20\%$ the current value has to be divided by $264 \mu\text{F}/C_{VSP}$ (see Table 7).

Table 8 Supply Pin VCC

2.2.8 Supply Pin VDP

Pin VDP delivers an internally generated supply voltage to internal loads only. The supply is generated by a series regulator. Internal input voltage for VDP is VDDH. Supply VDP is the positive supply for the mode control pins and DIV and TSTIN BDS pins.

Symbol	Parameter	Min	Max	Unit	Note	
V _{IN}	input voltage	4.75	V _{VSP}	V		
V _{VDP}	Internal supply voltage	3.0	3.6	V		
C _{VDP}	external storage capacitance	176	264	nF	1)	
I _{VDP}	external load at VDP		0	mA	2)	
1) Low ESR < 0.1 Ohms						
) In the explication there chould be no external load on VDD						

In the application there should be no external load on VDP.

Table 9 Supply Pin VDP

2.2.9 Supply Pins VDDH and VSSH

Pin VDDH and VSSH deliver an internally generated supply voltage to internal loads only. The VDDH supply is connected to the VSP externally by a short circuit. The VSSH supply is generated by a series regulator to provide a voltage to control the DC-DC converter. Internal input voltage for VSSH is VDDH which is supplied from the external voltage VSP.

Symbol	Parameter	Min	Max	Unit	Note
V _{VDDH}	Internal supply voltage	6.25	V _{VSP}	V	
V _{SSH}	Internal supply voltage	V_{VDDH} -3.6	V_{VDDH} -3.0	V	
C _{VSSH}	external storage capacitance	176	264	nF	1)
I _{VSSH}	external load at VSSH		0	mΑ	
IVDDH	external load at VDDH		0	mA	
1) Lov	w ESR < 0.1 Ohms				

Table 10 Supply Pins VDDH & VSSH

Technical Manual

pages 43

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2.2.10 Supply Pin V20 and Pin R20

Pin V20 delivers the internally generated supply voltage to external loads. The supply is generated by a series regulator. Internal input voltage for V20 is VDDH. The V20 regulator is switched off during softstart, making V20 unavailable

An external short-circuit from the V20 pin to VB- will not cause a destruction of the ASIC, interference on the bus or disturb generation of VCC. Relation V20(I_{V20}) shall have a fallback characteristic in order to limit the power loss.

The maximum current available from the V20 regulator can be reduced by adding an external resistance connected between the R20 pin and VB-. The R20 pin can be left open circuit if no reduction in maximum current is required.

In an applications where the V20 regulator is not going to be used pin 25 V20PD can be used to disable the V20 regulator. The pin should be hard wired to VB- for normal V20 operation and hard wired to VDP to disable the V20 regulator. The pin should not be used to dynamically control the state of the V20 regulator when the device is powered up. The CV20 capacitor can be removed from the application when V20PD is active (hard wired to VDP)

The IV characteristic of the regulated voltage should not cross the resistive load line defined by $R_{LL} = V_{V20(min)} / I_{V20}$.

Symbol	Parameter	Min	Max	Unit	Note		
V _{V20}	supply voltage (when current limit is not active)	17.5	22.5	V	1)		
C _{V20}	external storage capacitance	8	1200	μF	6)		
C _{V20}	external storage capacitance when V20PD is active	0		μF			
I _{V20}	Load current with current limiting not active		25	mA	2)8)		
I _{V20 ILIM}	Load current with current limiting active		30	mA	3)		
IV20 SHORT	Load current under short circuit conditions	5	16	mA	4)		
1) $V_{VSP} \ge V_{V20} + V_{DROP}$; for static load currents in the range defined by I_{V20} ; $V_{DROP} \le 1V$ 2) maximum allowed load at V20 for full output voltage. 3) current limitation of fallback characteristic 4) in case of short circuit: V20 connected with VB- VB+=30V, VSP = 29.5V							

5) power limitation of fallback characteristic

6) In parallel with ceramic 100nF

7) External resistor tolerance of $\pm 1\%$

8) If $C_{VSP} < 330 \ \mu F \pm 20\%$ the current value has to be divided by $264 \mu F/C_{VSP}$ (see Table 7).

Table 11 Supply Pin V20

Symbo I	Parameter	R20	Unit	IV20	Unit	Tol	Uni t
R20	External maximum current setting resistance	262	kΩ	5	mA	0 to +5	mA
		345	kΩ	10	mA	0 to +5	mA
		520	kΩ	15	mA	0 to +5	mA
		1000	kΩ	20	mA	0 to +5	mA
		o/c	kΩ	25	mA	0 to +5	mA
Footnote	8) of Table 11 has to be considered						

Table 12 External maximum current setting resistance



Figure 3 V20 Fallback Characteristic

2.2.11 Pin IND, SMPS-output

The pin IND is the output of the switched mode power supply. Internally the node is clamped to VB-. The voltages and currents depend on the switched mode power supply concept.

pages 43

2.2.12 Pin SVCC

This input pin controls the value of VCC. It is possible to switch between 3.3 V and 5 V. If pin SVCC is connected to VB-, VCC-voltage is 3.3 V. If pin SVCC is connected to VCC, VCC-voltage is 5 V. In any case it is necessary to connect SVCC to a defined level.

2.2.13 Receive Pin RxIN

The Receive Pin RxIN is coupled to the EIB bus by an external capacitor.

Symbol	Parameter	Min	Max	Unit	Note
C _{REC}	external coupling capacitance	44.5	49.5	nF	typ. 47 nF
1) AC coup	led by external capacitor 47 nF \pm 5%				

Table 13 Receive Pin RxIN

2.2.14 Transmit Pin TxO

The transmit pin is connected to VB+ via external resistor of typ. 68 Ω .

Symbol	Parameter	Min	Max	Unit	Note
dV_{BUS}	delta(V _{BUS}) during active LOW pulse	-6	-9	V	1)
1) related t	o VB+				

Table 14 Transmit Pin TxO

2.2.15 Supply Pin VIF

The Pin VIF is used as supply voltage for the pins TxD, RxD, RESn, SAVE, TSTOUT_TW, X1, X2 and determines their high input or output level.

Symbol	Parameter	Min	Max	Unit	Note		
VIF	external supply voltage for interface	3.0	5.5	V	1)		
C _{VIF}	external decoupling capacitor	10		nF	2)		
1) typical supply voltages: 3.3 V or 5 V							
Ω recommended, should be placed as place as percential between ME and ediment MD , device pine							

2) recommended; should be placed as close as possible between VIF and adjacent VB- device pins.

Table 15 Supply Pin VIF

2.2.16 Oscillator Pins X1 and X2

The oscillator Pins X1 and X2 are used for directly connecting a crystal of 4.9152 MHz without additional external capacitors. The tolerance of the oscillator is set by the parameters of the external crystal, and is expected to be +/-0.05 %.

It is possible to drive the ASIC by an external clock by forcing the X1 with the external clock; pin X2 must be open

In Analog Mode no external XTAL is needed and the XTAL oscillator does not run. In this case X1 must be connected to VIF or VB-, X2 must be open.

Symbol	Parameter	Min	Max	Unit	Note		
V _{X1/2}	Oscillator voltage at X1 and X2	-0.5	VIF + 0.5	V			
V _{IL}	voltage range for input low level		0.3 * VIF				
V _{IH}	voltage range for input high level	0.7 * VIF					
f _{clk}	clock frequency for external clock	2.4576	4.9152	MHz	1)2)		
1) 4.9	152 MHz or 2.4576 MHz, no other clock frequencies						
2) Cr	ystal Data (T _{amb} : -20 to 70 °C): 0 $\Omega \leq E.S.R \leq$ 91 Ω , 0	C _L =16 pF (n	nin: 15 pF, ma	ax. 21 pF),		
Dri	ve Level _{max.} = 60 μ W, C ₀ < 5 pF						
Cry	Crystal Data (T_{amb} : -25 to 85 °C): 0 $\Omega \leq E.S.R \leq 84 \Omega$, C _L =16 pF (min: 15 pF, max. 21 pF),						
Dri	ve Level _{max.} = 60 μ W, C ₀ < 5 pF						
	Table 16 Oscillator Pins X1 ar	nd X2					

2.2.17 Interface Pin RxD

The UART interface input pin RxD receives the information from host electronic to control the transmitter of the ASIC. This pin is an input pin with pull-down resistor. The switching levels are derived from external supply voltage VIF.

In normal mode: $RxD = LOW \rightarrow RxD3 = HIGH \rightarrow transmitter switches on In analog mode: <math>RxD = HIGH \rightarrow RxD3 = HIGH \rightarrow transmitter switches on$

Symbol	Parameter	Min	Max	Unit	Note
V _{IL}	voltage range for input low level		0.3 * VIF		
V _{IH}	voltage range for input high level	0.7 * VIF			
V _{hvst}	hysteresis for switching level	0.1 * VIF	0.4 * VIF		1)
R _{PullDown}	value of internal pull-down resistor	150	450	kΩ	
1) switchin	g level approx, VIF/2, i.e. VIF/2 + V _{buet} /2				

Table 17 Interface Pin RxD

2.2.18 Interface Pin TxD

The UART interface output pin TxD transmits the information to host electronic. The high output level is derived from external supply voltage VIF.

In normal mode: LOW pulse at EIB bus \rightarrow TxD3 = HIGH \rightarrow TxD = LOW In analog mode: LOW pulse at EIB bus \rightarrow TxD3 = HIGH \rightarrow TxD = HIGH

Symbol	Parameter	Min	Max	Unit	Note
V _{OH}	output voltage high	VIF - 0.5		V	I _{он} = -5 mA
V _{OL}	output voltage low		0.4	V	I _{OL} = 5 mA
t _{r,} t _f	rise time, fall time (10 % \leftrightarrow 90 %)		100	ns	C _L = 150 pF

Table 18 Interface Pin TxD

2.2.19 Switching Pin STxO

The switching pin STxO is an open drain output with an external pull-up resistance. It is driven to provide a high output level during transmission. In all modes where the digital part is active an internal signal generated by the digital part and used to control the switching of STxO. It switches from LOW to HIGH before (typ. 500 μ s) the first transmit signal. In all modes where the digital part is

Technical Manual

not active Table 19 Switching Pin STxO applies. The control for the switching of STx0 is derived from the send pulse width limitation implemented within the analog part. The high output level is derived from an external supply voltage.

Symbol	Parameter	Min	Max	Unit	Note
V _{STx0}	External supply voltage for STx0	VIF	50	V	4)
V _{OH}	output voltage high		50	V	4) 5)
V _{OL}	output voltage low		0.4	V	I _{OL} = 5 mA
t _{DELAY}	delay time from active RxD to STxO L/H (50%		300	ns	1) 2)
	 ↔ 50%)				
t _{SENDMAX}	delay time from inactive RxD to STxO H/L	1.5	2	ms	3)
	(50% ↔ 50%)				
t _r	rise time (10 % \rightarrow 90 %)			ns	5)
t _f	fall time (90 % \rightarrow 10 %) for V _{STx0} =30V		900	ns	C _L = 150 pF
	ns	C _L = 150 pF			
1) When the	ne digital part is not active the STxO L/H is trigger	ed / retrigger	red by an act	ive RxD s	signal.

2) In normal mode the Digital part controls the STxO transitions with regard to the RxD signal.

3) When the digital part is not active.

4) during surge impulse: -20 V for 2 µsec and +65 V for 150 µsec

5) I_{OH} and t_r are set be external pull-up resistance.

Table 19 Switching Pin STxO

2.2.20 Reset Pin RESn

This pin is an I/O pin with internal pullup resistor to VIF. In reset case the reset pin delivers an active LOW signal to external host electronic. The output driver is realized as open drain. The reset state RESn = LOW can be caused by an internal or by an external RESET due to forcing an active LOW to the pin RESn. The switching levels are derived from external supply VIF.

Symbol	Parameter	Min	Max	Unit	Note
R _{PullUp}	value of internal pull-up resistor to VIF	10	25	kΩ	
V _{RESmax}	maximum voltage at RES pin		VIF + 0.5	V	
V _{IL}	voltage range for input low level	0	0.3 * VIF		
V _{IH}	voltage range for input high level	0.7 * VIF	1.0 * VIF		
V _{hyst}	hysteresis for switching level	0.1 * VIF	0.4 * VIF		1)
V _{OL}	output low voltage		0.2	V	2)
t _f	fall time (90 % \rightarrow 10 %) for VIF = 5.25V		100	ns	C _L =
					150 pF
					3)
1) switch	ing level approx. VIF/2, i.e. VIF/2 ±V _{hvst} /2				
2) I _{OL} of	1mA when VIF=1V; I_{OL} of 5mA when VIF \ge 3V				
3) Rise ti	me determined by R_{PullUp} , C_{L} and VIF				

Table 20 Reset Pin RESn

2.2.21 Mode Control Pins MODE0, MODE1, MODE2, MODE3 TESTMODE and CTM

These input pins are used to control the mode of the ASIC by connecting them to VB-(0) or VDP(1).

The normal operating mode is reached with MODE0 =1, MODE1 =1, MODE2=0, MODE3=0, TESTMODE =0 and CTM=0. Section 1.2 "Selection of Different Modes of Operation" shows the different modes selected by the MODE<0:2> and TESTMODE pins and the usage of the other pins in these modes.

Symbol	Parameter	Min	Max	Unit	Note
V _{IL}	voltage range for input low level	0	0.3 * VDP	V	
V _{IH}	voltage range for input high level	0.7 * VDP	1.0 * VDP	V	

Table 21 Mode Control Pins MODE0, MODE1, MODE2, MODE3, TESTMODE & CTM

2.2.22 Pin TSTIN_BDS

In normal mode it is used as input pin to select the baud rate of the UART interface to the host electronic.

Symbol	Parameter	Min	Max	Unit	Note
VIL	input low level (UART baud rate 19.2 kBaud)	0	0.3 *		
			VDP		
VIH	input high level (UART baud rate 115.2 kBaud)	0.7 * VDP	1.0 *		
			VDP		

Table 22 Pin TSTIN_BDS

2.2.23 Pin TSTOUT_TW

TW = HIGH means: chip temperature is higher than maximum allowed value and TxO is disabled.

Symbol	Parameter	Min	Max	Unit	Note
V _{OH}	Output HIGH voltage	VIF - 0.5		V	I _{он} = -5 mA
V _{OL}	Output LOW voltage		0.4	V	I _{OL} = 5 mA
t _r , t _f	rise time, fall time (10 % \leftrightarrow 90 %)		100	ns	C _L = 150 pF

Table 23 Pin TSTOUT_TW

Technical Manual

2.2.24 Pin SAVE

This pin is an open drain output with internal pull-up resistor to VIF.

In case of break-down of the bus voltage for more than typ. 1.5 ms (save condition) this pin delivers an active LOW signal to external host electronic.

Symbol	Parameter	Min	Max	Unit	Note
R _{PullUp}	Value of internal pull-up resistor to VIF	10	25	kΩ	
V _{max}	maximum voltage at SAVE pin		VIF + 0.5	V	
V _{OL}	output low voltage		0.2	V	1)
t _{FRG2}	Delay from VB+ break-down to SAVE= LOW	0.7	3	ms	Typ. 1.5 ms
t _f	fall time (90 % \rightarrow 10 %)		100	ns	C _L = 150 pF 2)
 I_{OL} of 1r Rise time 	mA when VIF=1V; I_{OL} of 5mA when VIF ≥ 3V the determined by R_{PullUp} , C_L and VIF	1	1		, , , , , , , , , , , , , , , , , , , ,

Table 24 Pin SAVE

2.2.25 Pin DIV

This input pin activates an internal 2:1 clock divider. If a 4.9152 MHz clock is used (quartz or external clock) then pin DIV must be connected to VDP. If an 2.4576 MHz clock is used (only external clock) then this pin must be connected to VB-.

Symbol	Parameter	Min	Max	Unit	Note
V _{IL}	voltage range for input low level	0	0.3 * VDP		
V _{IH}	voltage range for input high level	0.7 * VDP	1.0 * VDP		

Table 25 Pin DIV

Digitalpart 3

TP-UART 2+ is at the digital interface compatible with TP-UART. This means that the same drivers and stacks can be used without modification.

In addition TP-UART 2+ supports some additional useful services. These services reduce the necessary performance in the microcontroller.

3.1 **Relationship to ISO-Reference-Model**



EIB - UART - Layer

Fig. 1: ISO/ OSI Layer

Tasks of the Logical Link - Control in: Checksum, Parity, Immediate Acknowledge, Repetition, Timing TP-UART: Host - Controller : Checksum, Parity, Addressing, Length

pages 43

3.2 UART – Interface to host controller

3.2.1 Configuration and Timing

The TP-UART-IC has a full duplex UART-interface to transmit and receive KNX frames asynchronously. The baud-rate depends on the setting of BDS pin (115200 or 19200). The frame format consists of a start bit (=0), eight data bits (LSB first), an even parity bit and one stop bit (=1)



The parity bit of every received byte from the host will be checked by the TP-UART. Errors will be reported to the host controller. Erroneous bytes (faulty parity) from EIB receiver will be checked too, but the host won't be informed. In those cases the host controller has to recognize the parity faults in the transmitted telegrams by its own. The UART receiver accepts frames up to a maximum baud rate deviation of 3%.

3.2.2 Resetbehavior

After connecting the operating voltage the TP-UART-IC generates an active reset (level 0 V) at pin RESn. This is valid for all modes. If Normal Mode is activated the following will happen at the UART-interface.

TxD will be 0 as long as there was no bus signal on the EIB for 40 Tbit (1 Tbit = 1/9600 s; Attention: The bittime of RxD/TxD depends on the adjusted baud rate at the UART-interface, for example 1/12Tbit or 0,5 Tbit). This results in a complete time of 40 Tbit + 12 Tbit = 5,42 ms. Then TxD changes for 1 Tbit to 1 and following the service TP-UART-Reset.Indication is transmitted. This signal behavior on TxD appears after each reset.

3.2.3 UART-Protocol Definition

The protocol between TP-UART-IC and the application controller is a two wire protocol with software handshake. Each data byte transmitted to the TP-UART-IC is started with a control byte. Each data byte received on the EIB is transparently transmitted through the TP-UART-IC and is therefore started with the EIB control field. Additional Information from the TP-UART-IC is transmitted with an ESC code on the EIB control field. The host controller which is connected to the TP-UART-IC needs either to detect a receive time-out of 2 to 2,5 ms to detect an end of Packet or check the CRC16-CCITT.

3.2.3.1 Services to UART

The following Services are supported from the TP-UART-IC.

- U_Reset.request
- U_State.request
- U_ActivateBusmon
- U_AckInformation (Nack, Busy, Addressed)

pages 43

- U_ProductID.request
- U_ActivateBusyMode
- U_ResetBusyMode
- U_MxRstCnt + Repetitions
- U_ActivateCRC
- U_Set_Address +PhysAddressHigh +PhysAddressLow
- U_L-Data Start + CTRL-Byte
- U_L-Data Continue (index) + Data-Byte
- U_L-Data-End + Checksum
- U_PollingState (Slotnumber) + PollAddrHigh + PollAddrlow + State

l	Uar	t-C	on	tro) F	iel	d	Sonvisonama	Цох
7	6	5	4	3	2	1	0	Servicename	пех

-											
0	0	0	0	0	0	0	1	U_Reset.request	01]	
0	0	0	0	0	0	1	0	U_State.request	02]	
0	0	0	0	0	1	0	1	U_ActivateBusmon	05]	
0	0	0	1	0	n	b	а	U_AckInformation	10-17	n,B,a:	Nack,Busy,Addressed
0	0	1	0	0	0	0	0	U_ProductID.request	20]	
0	0	1	0	0	0	0	1	U_ActivateBusyMode	21]	
0	0	1	0	0	0	1	0	U_ResetBusyMode	22]	
0	0	1	0	0	1	0	0	U_MxRstCnt	24]	
0	0	1	0	0	1	0	1	U_ActivateCRC	25]	
0	0	1	0	1	0	0	0	U_SetAddress	28]	
]	
1	0	0	0	0	0	0	0	U_L_DataStart	80]	
1	0	i	i	i	i	i	i	U_L_DataContinue	81-BE	i = Index	1 62
0	1	Ι	Ι	Ι	Ι	Ι	Ι	U_L_DataEnd	47-7F	I = length	7 63
1	1	1	0	s	s	s	s	U_PollingState	E0-EE	s= Slotnumber	0 14

Fig. 3: Uart-Control Field

3.2.3.1.1 U_Reset.request-Service

Resets the TP-UART-IC to the initial state and clears all buffers. At start-up the TP-UART waits for a bus free-time-out before sending a U_Reset.indication-Service to the host. To be sure that the TP-UART is reset after power up the host shall wait for 50 ms after reset signal is high and then send the U_Reset.request-Service.

UART-Controlfield (01 _{hex})									
7	6	5	4	3	2	1	0		
0 0 0 0 0 0 1									
				-					

Fig. 4: U_Reset.request-Service

Technical Manual

pages 43

3.2.3.1.2 U_State.request-Service

Requests the internal communication state from the TP-UART-IC. The TP-UART-IC answers with the Communicationstate.

UART-Controlfield (02 _{hex})								
7	6	5	4	3	2	1	0	
0	0	0	0	0	0	1	0	

Fig. 5: U_State.request-Service

3.2.3.1.3 U_ActivateBusmon-Service

Activates the busmonitormode. That means that each byte which is received on the EIB is sent through the TP-UART-IC including illegal Control-bytes and not used Immediate ACK. The TP-UART-IC is absolutely quiet on the EIB. The busmonitormode can only be left by using the U_Reset.request-Service.

UART-Controlfield (05 _{hex})									
7	6	5	4	3	2	1	0		
0	0	0	0	0	1	0	1		
			-						

Fig. 6: U_ActivateBusmon

3.2.3.1.4 U_ProductID.request

Requests the internal TP-UART-IC product identifier. The TP-UART-IC answers with the U_ProductID.response service

UART-Controlfield (20 _{bex})									
7	7 6 5 4 3 2 1 0								
0 0 1 0 0 0 0 0									

Fig. 7: U_ProductID.request

3.2.3.1.5 U_ActivateBusyMode

If the host controller is temporarily not able to receive telegrams from the bus (e.g. due to no code execution during flash erase), the TP-UART should reject frames from the bus with BUSY acknowledges. The service activates the BUSY mode in the TP-UART for a fix period of 700 ms (+/-10ms). This means that all addressed telegrams (TP-UART has internally the "addressed" bit set) are acknowledged with Busy.

Note: physical addressed frames which do not correspond with the TP-UART address will never be acknowledged with BUSY!

All received telegrams are sent byte by byte from the TP-UART to the host as before. If the host confirms a frame with the U_Ackinfo service (ACK, NACK or BUSY) the BusyMode will be deactivated. After reset the BusyMode will be also deactivated.

	UART-Controlfield (21 how)									
_	-	-	001101				-			
7	6	5	4	3	2	1	0			
0 0 1 0 0 0 1										

Fig. 8: U_ActivateBusyMode

3.2.3.1.6 U_ResetBusyMode

The service U_ResetBusyMode deactivates immediately the BUSY mode in the TP-UART. All addressed telegrams are answered according to the intern address flags. The host shall synchronize its receiver before sending the U_ResetBusyMode.

UART-Controlfield (22 _{hex})								
7	6 5 4 3 2 1 0							
0 0 0 1 0 1 0								

Fig. 9: U_ResetBusyMode

3.2.3.1.7 U_SetAddress

This service configures the physical address of the TP-UART. If this service is repeatedly sent (e.g. the physical address changes), the new address will be active in the TP-UART after reception of the complete U_SetAddress service and when no Layer 2 frame is currently received from the EIB. If the address is set a complete address evaluation in the TP-UART is activated (group-addressed telegrams are now generally confirmed).

Note: The TP-UART does not evaluate the received EIB telegrams which were sent itself. After reset the address evaluation is deactivated again.

UART-Controlfield (28 _{hex})									
7	7 6 5 4 3 2 1 0								
0	0	1	0	1	0	0	0		

physical address high							physical address low								
7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
a a a a l l l l							d	d	d	d	d	d	d	d	

Fig. 10: U_SetAddress

The TP-UART analyzes after setting the physical address independently of the host controller all telegrams and evaluates the destination address. If addressed then the IACK generation takes place. The TP-UART analyses for this reasons the different frame formats (standard frame and extended frame format according to the KNX standard).

- Frameformat Standard:

Octet 0	 Octet 3	Octet 4	Octet 5	
Ctrlbyte	 High byte	Low byte	NPCI	
1 0R1cc00	destaddress	destaddress	Axxx xxxx	

- Frameformat **Extended**:

Octet 0	Octet 1	Octet 4	Octet 5	
Ctrlbyte	extCtrlbyte	High byte	Low byte	
0 0R1cc00	Axxx xxxx	destaddress	destaddress	

a) group (multicast) or broadcast addresses if (A == 1) then group addressed

=> "addressed"

b) physical addressed (point to point)

if $(\mathbf{A} == 0)$ then physical addressed

=> if (destination address == physical address of TP-UART)

=> "addressed"

If the TP-UART is "addressed" and no error occurs then the TP-UART sends an IACK. If the TP-UART is "addressed" and an error occurs (parity or checksum error) then it generates an INACK.

Note:

Also during activated address evaluation the host is able to manipulate the IACK generation of the TP-UART by sending the U_AckInformation service.

3.2.3.1.8 U_AckInformation-Service

The U_AckInformation-Service is only sent to the TP-UART if a host controller wants to check the destination address itself. This service is sent by the host after the address evaluation and must be sent latest 2,8 ms after receiving the address type octet of an addressed frame. The Nack-/ Busy-/ Addr-Bits sets internal flags in the TP-UART. The NACK flag is set by the TP-UART itself if it is detecting any frame error.

If the TP-UART receives this service and the addressed bit is set it will generate a ACK, NACK or <u>BUSY-frame on the EIB depending on the settings</u> of the NACK/busy-flags.

	UAR I-Controlfield										
7	7 6 5 4 3 2 1 0										
0 0 0 1 0 x x x											
	Ackl	nforma	ation		Nack	Busy	Addr				

Fig. 11: U_AckInfo-Service



Fig. 12: Timing for send U_AckInfo(e.g. 19200 Baud)



Fig. 13: Ack / Nack / Busy Generation of the TP-UART

Technical Manual

pages 43

3.2.3.1.9 U_L_Data-Services

The U_L_Data-Services are used to transfer the complete EIB-Linklayer-Frame (L_Data.request and L_PolIData.request) to the TP-UART.

If the host sends a second frame (the first frame buffer is yet active) the TP-UART rejects this and reports it with a Status.indication (PE bit set).

HOST



Fig. 14: TP-UART send telegram



Fig. 15: TP-UART receive telegram

3.2.3.1.9.1 U_L_DataStart-Service

The U_L_DataStart-Service initialize the TP-UART-IC to receive a complete EIB-Linklayer-Frame from the host. As additional data the EIB-Control-byte is transmitted which is the control field of the L_Data-frame or L_Polldata-frame. If the repetition flag in the control byte is just cleared the TP-UART transmits the frame only once time with repetition flag set.

	UART-Controlfield (80 _{hex})									Addi	tional	nform	ation		
7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
1	0	0	0	0	0	0	0	F	F	R	1	С	С	0	0
	L-Data	L-Data Data-Index 00 = Start								E	IB-Cor	ntrolfie	ld		

Fig. 16: L_DataStart Service

FF = Frame Format

10 Standard Length L_DATA service

00 extended L_DATA service

```
11 L_POLLDATA service
```

R = Repeatflag (on the EIB 1 = not repeated, 0 = repeated)

1 = repeat the telegram on the EIB (see U_MxRstCnt service, default 3 times)

send first time with repeatflag = 1 and repeat with repeatflag = 0

```
0 = don't repeat the telegram on the EIB; send only one time with repeatflag = 1
```

cc = class

Technical Manual

pages 43

control field	data link frame type	class	repeat flag
FFR1 cc00			
FFR1 0000	L_DATA request	system	set by TP-UART
FFR1 1000	L_DATA request	alarm	set by TP-UART
FFR1 0100	L_DATA request	high	set by TP-UART
FFR1 1100	L_DATA request	normal	set by TP-UART
1111 0000	L POLLDATA request	system priority	= 1

Fig. 17: Legal EIB-Controlfield

3.2.3.1.9.2 U_L_DataContinue-Service

The U_L_DataContinue-Service transmits one byte of the contents of an EIB-L_Data-Frame to the TP-UART. The data-index starts with 1 and the maximum value is 62 depending on the length of the frame.

		U	ART-C	ontrolfi	eld					Addi	tional	Information	ation		
7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
1	0	i	i	i	i	i	i	d	d	d	d	d	d	d	d
L-D)ata		Da	ta-Inde	ex (1 –	62)			EIB	-Data	Byte fo	or L-Da	ta-Fra	me	

Fig. 18: U_L_DataContinue-Service

3.2.3.1.9.3 U_L_DataEnd-Service

The U_L_DataEnd-Service marks the end of the transmission of the EIB-Frame. After receiving this service the TP-UART checks the checksum and if correct the transmission starts on the EIB else the UART returns a state-indication with Receive-Errorflag is set.

		UAR1	-Contr	olfield	(80 _{hex})					Addi	tional	nforma	ation		
7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
0	1	Ι	Ι	I	1	1	1	С	С	С	С	С	С	С	С
L-D)ata		L	_ength	(7 - 6)	3)					Chec	ksum			

Fig. 19: U_L_DataEnd-Service

3.2.3.1.9.4 U_MxRstCnt

This service adjusts the maximum number of repetitions on bus after a frame has not been acknowledged with IACK. Values from 0 to 7 are separately adjustable for BUSY or INACK. No acknowledge will be handled as INACK. If the host clears the repetition flag in the U_L_DataStart service always no repetitions will be sent.

After Reset 3 repetitions are active.

		UART	-Contr	olfield	(24 _{hex})						MxR	stCnt			
7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
0	0	1	0	0	1	0	0	С	С	С	0	0	С	С	С
								В	usy Cr	nt			N	ack Cr	nt

Fig. 20:U_MxRstCnt

3.2.3.1.9.5 U_ActivateCRC

This service activates a 16 bit CRC calculation for every received Layer 2 Service from the bus (except when the TP-UART is Polling Slave or the busmonitormode is active). However the CRC calculation only becomes active at the host speed of 19200 Baud.

The TP-UART calculates over the complete received telegram (including the Layer 2 checksum) a CRC16-CCITT with the following parameters:

- Width= 16 bit
- Truncated polynomial = 1021hex
- init value = FFFFh
- I/O not reflected
- no xor on output CRC
- Test string "123456789" is 0xE5CC

and adds it to the receiving frame (sending order is highbyte then lowbyte).

After Reset CRC calculation is disabled.

		UAR	T-Cor	trolfiel	d (25 _{he}	ex)		
7	6	5	4	3	2	1	0	
0	0	1	0	0	1	0	1	
T in	04.11	Active		`				

Fig. 21: U_ActivateCRC

3.2.3.1.9.6 U_PollingState

This service must be send to the TP-UART if an Pollingframe-Ctrlbyte is received. If the TP-UART detects a collision during sending the slave slot to the EIB the TP-UART generates a State indication with the Slave Collisionflag set.

		UA	ART-Co	ontrolfi	eld					Poll	ing Ad	dress l	high		
7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
1	1	1	0	s	S	S	s	С	С	С	С	С	С	С	С
					Slotnu	umber									

		Pol	ling Ac	dress	low						Pollin	gstate			
7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
С	С	С	С	С	С	С	С	С	С	С	С	С	С	С	С

Fig. 22: U_PollingState-Service

																																												Π	Π	ī				Т	Т	Τ	Т	Т	Π
			Ct	rl-I	Byt	e							5	Src	-A	dd	r								S	rc-	Ac	ldr								Pc	١Ā	dd	r					Π		P)II	٩d	dr				T		
Receive from Bus	s 0	1	2	3	4 !	56	5 7	р	s	s	0	1	2	3	4	5	6	7 p) s			s	0	1	23	4	5	6	7	ps	s		s	0	1	2	34	15	6	7	p	s			s	0	1	2	3	4 !	56	ô 7	/ p) s	
																																																					Ι		
												С	trl-	·By	/te																								Γ					Π		1						Т	Т	T	
Send to Controller										sl) 1	2	3	4	5	6	7	0	S																																		Ι		
																																												Π		1				Т		Т	Τ	Τ	
																						Po	IIC	trl-	١S	otr	nr							F	Pol	IAd	ddr								_		Pc	ЫİÂ	٨d	dr					
Rec from Controller																				s	0	1	2	3	4 5	6	7	р	s		5	s C) 1	2	3	4	56	6 7	'p	s			s	0	1	2	3	4	5	6	7 r	ρε	\$		s
																					1																		1					Π						Τ	Τ	Τ	Т	Τ	П
																				Т						Т	Γ		Τ				Т						Т		Γ			Π						Т	Т	Т	Т		
Send to Bus																																																					T		
																																	Γ																		Т	Т	Т		Г

	PollAddr	Slotcount	Checksum	Slot 0	
Receive from Bus	s 0 1 2 3 4 5 6 7 p	s s 0 1 2 3 4 5 6 7 p s	s 0 1 2 3 4 5 6 7 p s	s 0 1 2 3 4 5 6 7 p s	s 0 1 2
Send to Controller					
Rec From Controller	PollAddr s 0 1 2 3 4 5 6 7 p s	Pollingstate s 0 1 2 3 4 5 6 7 p s			
Send to Bus				Slot 0 s 0 1 2 3 4 5 6 7 p s	

Fig. 23: Timing for U_PollingState-Service (Host is slave)

																																																								Τ	٦
				Ct	rl-E	Byte	Э.							5	Src	-A	dd	lr								S	rc-	Ac	ldr							F	Pol	IAd	ddr	•						F	20	ΠA	١d	dr							
Send to Bus		s C) 1	2	34	15	6	7	o s			s () 1	2	3	4	5	6	7	o s			s	0	1	23	34	5	6	7 p	o s	;		s	0	1	23	3 4	5	6	7	р	s		Ś	s () ·	1	2	3	4	5	6	7	0	s	
				Ct	rl-E	3yte	9							2	Src	-A	dd	r								S	rc-	Ac	ldr							F	Pol	IAd	ddr							F	°0	οIIA	٩d	dr							
Receive from Bus		s C) 1	2	34	15	6	7	p s			s () 1	2	3	4	5	6	7	o s			s	0	1	23	34	5	6	7 p	o s	;		s	0	1	23	3 4	5	6	7	р	s		\$	s () ·	1	2	3	4	5	6	7	0	s	
													C	trl	-By	/te									S	rc-	Ado	dr								S	Src	-A	dd	r							F	Pol	II A	٩d	dr						
Send to Controller											s	0	1 2	23	4	5	6	7	ps	S		s	0	1	2	3 4	15	6	7	ps	5		s	0	1	2	3 4	15	6	7	р	s			s () ſ	1	2	3	4	5	6	7	0	s		
														Γ						Τ		1																																		Τ	
	Π									Γ				Γ						Т	Т	I	Pol	IIC	trl+	+SI	otr	۱r		Т				Γ	P	oll	Ad	dr						Т			F	20	IIA	١d	dr					Т	
Rec from Controller																					s	0	1	2	34	4 5	56	7	р	s		s	0	1	2	34	4 5	56	7	р	s			s١	0	1 2	2	3	4	5	6	7	ps	s			s
	Π													Γ						Τ																																				Т	

	PollAddr	Slotcount	Checksum	Fillbyte for Slot0	
Send to Bus	s 0 1 2 3 4 5 6 7 p	s s 0 1 2 3 4 5 6 7 p s	s 0 1 2 3 4 5 6 7 p s	s 0 1 2 3 4 5 6 7	osss s0123
	PollAddr	Slotcount	Checksum	Slot 0	Slot
Receive from Bus	s01234567p	s s 0 1 2 3 4 5 6 7 p s	s 0 1 2 3 4 5 6 7 p s	s 0 1 2 3 4 5 6 7 p s	s s 0 1 2 3 4
	PollAddr	PollAddr	Slotcount	Checksum	Slot 0
Send to Controller	01234567ps	s 0 1 2 3 4 5 6 7 p s	s 0 1 2 3 4 5 6 7 p s	s 0 1 2 3 4 5 6 7 p s	s 0 1 2 3 4 5 6 7 p s
	PollAddr	Pollingstate			
Rec From Controlle	r 0 1 2 3 4 5 6 7 p s	s 0 1 2 3 4 5 6 7 p s			

Fig. 24: Timing for U_PollingState-Service for a Master

3.2.3.1.9.7 Services from UART

The first character of each service sent to the host is the control field. The control field contains the information about the TP-UART-Service. There are 3 types of services sent to the host, the EIB-Layer-2-Services, immediate acknowledge services and the special TP-UART-Services. The EIB-Layer-2-Services contains information about its class and a flag containing the information whether the LPDU is a repeated one. The immediate acknowledge services are only sent in busmonitormode and includes informations about successful sending. The TP-UART-Services are to inform the host about the communicationstate or to reset the communication.

76	Cor 5	ntro 4	ol F 3	iel 2	d 1	0				
Laye	er-2	S	erv	ice	es					
	repeat flag		class	class				repe fram	at flaç e	g = 0: repeated L_DATA
1 0	r	1	c1	c0	0	0	L_DATA.req	c1	c0	
0 0	r	1	c1	c0	0	0	L_EXT_DATA.req	0	0	system priority
1 1	1	1	0	0	0	0	L_POLLDATA.req	1	0	urgent priority
Imm	edi	ate	e A	ck	no	wle	edge Services	0	1	normal priority
1 1	0	0	1	1	0	0	Acknowledge frame	1	1	low priority
0 0	0	0	1	1	0	0	NotAcknowledge frame			-
1 1	0	0	0	0	0	0	Busy frame			
TP-L	JAF	٦T	-Co	ont	rol	-S	ervices			
0 0	0	0	0	0	1	1	Reset-Indication			
x x	Х	х	x	x	х	х	ProductID.response			
x x	Х	х	х	1	1	1	State.response/indication			
x 0	0	0	1	0	1	1	L_DATA.confirm	x = 1	Posit	tive Confirm

Fig. 25: Control Field

3.2.3.1.10 Layer-2 Services

The Layer-2 Services includes all standard EIB-Linklayer Services. The Controlfields are followed by the data of the EIB-Frame. All bytes received on the EIB are immediately sent to the host. The host either has to detect an end of packet timeout by supervising the EOP gap of 2 - 2,5 ms or check the end of frame by calculating the CCITT CRC (must be enabled by the U_ActivateCRC service).

x = 0 Negative Confirm

control field	Hexadecimal	data link frame type	class	repeat flag
FFR1 cc00				
				(0 = repeated)
FF11 0000	30/B0 _{Hex}	L_DATA request	system	not repeated
FF01 0000	10/90 _{Hex}	L_DATA request	system	repeated
FF11 1000	38/B8 _{Hex}	L_DATA request	urgent	not repeated
FF01 1000	18/98 _{Hex}	L_DATA request	urgent	repeated
FF11 0100	34/B4 _{Hex}	L_DATA request	normal	not repeated
FF01 0100	14/94 _{Hex}	L_DATA request	normal	repeated
FF11 1100	3C/BC _{Hex}	L_DATA request	low	not repeated
FF01 1100	1C/9C _{Hex}	L_DATA request	low	repeated
1111 0000	F0 _{Hex}	L_POLLDATA request	system	

Fig. 26: Controlfield for Layer 2 Services

The Frameformat 01 is not supported.

For a complete description of the Linklayer service see the KNX Standard.

```
Technical Manual
```

pages 43

Each L_Data-request is transmitted completely to the Host. From a L_PollData-request only the Controlbyte is transmitted to the host if the TP-UART is a polling slave. If the TP-UART is polling master the complete polling frame is transmitted to the host as well if a collision is detected during sending the polling master frame.

If the 16 bit CRC calculation is enabled (see U_ActivateCRC, the host baud rate have to be 19200) then the Linklayer service follows a 16 bit CRC (order Highbyte, Lowbyte). The timing is fix for both supported baudrates. The high byte of the CRC is sent 6.5 Tbit after the last received octet from bus (calculated after stopbit) and the low byte is sent immediately afterwards.

																																				Τ	Τ				Τ		Π
																																				Τ					Τ		
						Da	ata							Ch	ec	ksι	ım														IAC	СК									Τ		
Receive from bus		:	s 0	1	2	3 4	15	6	7 F	P S	s	; 0	1	2	3 4	5	6	7	P S										s	0	12	2 3	34	5	6	7 F	۶						
								Π																								Τ				Т	T		Т		Т		
Send to Controller											Da	ta								C	hec	ks		CR	Cŀ	ΗB		CF	SC	LB						Τ	Т	со	nfi	rm	Т		
TPUART TXD (19200)																																										
																																				Τ	Τ		Τ		Τ		
																																			_						\perp		

Fig. 27: Timing for CRC 16 bit

3.2.3.1.11 Acknowledge Services

Acknowledge services are only transmitted to the host in busmonitormode. Note: In busmonitormode each received byte on the EIB is sent through the TP-UART-IC including illegal control bytes and not used Immediate ACK. The TP-UART-IC is in this mode absolutely quiet on the EIB.

The short acknowledgement frame format consists of 15 bit times idle time followed by a single character which is used to acknowledge an L_Data.req frame. The following Figure shows the corresponding codes of the short acknowledgement.

-								_
			Oct	et 0				
			Short	ACK				
8	7	6	5	4	3	2	1	
1	1	0	0	1	1	0	0	ACK
0	0	0	0	1	1	0	0	NAK
1	1	0	0	0	0	0	0	BUSY

Fig. 28: Short Acknowledgement Frame Format

3.2.3.1.12 TP-UART-Control Services

The TP-UART-Control service exist only on this interface. They are to reset the communication or to inform the host about the actual state.

3.2.3.1.12.1 TP-UART-Reset.indication Service

The Reset.indication service is sent after each reset if 40 bit-times line idle was detected.

		TP-L	JART-(Control	field		
7	6	5	4	3	2	1	0
0	0	0	0	0	0	1	1

Fig. 29: TP-UART-Reset.indication-Service

3.2.3.1.12.2 TP-UART-ProductID.response Service

The ProductIdentifier.response service is sent if a U_ProductID.request service was received from the host.

Release a: 0100 0001

		TP-L	JART-(Contro	lfield		
7	6	5	4	3	2	1	0
i	i	i	r	r	r	r	r
Produ	ict ID			revis	ion nu	mher	

Fig. 30: TP-UART-ProductID.response-Service

3.2.3.1.12.3 TP-UART-State.indication/response Service

The TP-UART-State.response-service is sent if an U_State.request-Service was received from the host. If the TP-UART is too hot (over-temperature), the TW-bit has the value 1. In case of Slave Collision, Receive Error, Checksum Error or Protocol Error or Recognition Over-Temperature or Recognition Leaving-Over-Temperature the TP-UART sends a State.indication-Service.

TP-UART-Controlfield											
7	6	5	4	3	2	1	0				
SC	RE	TE	PE	TW	1	1	1				

Fig. 31: TP-UART-StateIndication/Response-Service

SC = Slave Collision

RE = Receive Error (Checksum, Parity or Biterror)

TE = Transmitter Error (send 0 receive 1)

PE = Protocol Error e.g. illegal controlbyte

TW = Temperature Warning

Attention: A received L-Data-Frame can follow the State indication without any delay.

3.2.3.1.12.4 TP-UART-L_Data.confirm Service

The L_DATA.confirm service is transmitted to the host if an acknowledge was received or if the last repetition is transmitted and no acknowledge was received.

		TP-L	JART-0	Control	lfield		
7	6	5	4	3	2	1	0
Х	0	0	0	1	0	1	1

Fig. 32: TP-UART-L_DATA.confirm-Service

X = 1 The transmission of the L_DATA-frame was successful

X = 0 The transmission of the L_DATA-frame was not successful

Technical Manual

pages 43

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4 Mechanical Specification

4.1 Package



Figure 4 Package outline, Punched QFN 6x6x0.9mm 36LD 0.5mm Lead Pitch



Figure 5 Package dimensions, Punched QFN 6x6x0.9mm 36LD 0.5mm Lead Pitch (Variant C)

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BOD www.amkor.com БШ 6 X 6 MLF2, PACKAGE OUTLINE, TERMINALS. PRINTING IS AN ACTUAL SCALE ΗH BODΥ. 0.07mm . AS PACKAGE MAXIMUM(.012 INCHES MAXIMUM) EXPOSED PAD AS WELL OF THE Ш 1994. TOLERANCE MUST TOP SURFACE Ч TERMINAL AND IS MEASURED SHAPE SHOWN ON FOUR CORNERS ARE NOT ACTUAL 1/0. I FEATURE TO ASME Y14.5M. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL APPLIES ONLY FOR STRAGHT TIEBAR SHAPES. ઝ OR OTHER TERMINALS IN X-DIRECTION TERMINALS IN Y-DIRECTION. 비 TIP ΗH THE LEAD POSITION #1 IDENTIFIER MUST BE EXISTED ON BETWEEN 0.15 AND 0.30mm FROM TERMINAL ACTUAL MEAN VALUE OF BODY SIZE. 10 0.305mm PACKAGE BY USING INDENTATION MARK BILATERAL COPLANARITY ZONE APPLIES CONFORM ALL DIMENSIONS ARE IN MILLIMETERS. TO PLATED TERMINALS. APPLIED ONLY FOR TERMINALS. <u>0</u> TOLERANCES ALLOWABLE PITCH, Ю Ne IS THE NUMBER OF Ы **b** APPLIES HEREIN ARE THE DICULISME PROPERTY OF ANKOR INCEPTS CONTINUED REGEN ARE COMPUTED THAT PROPERTING TO AND SHALL NOT BE RELEVED TO ANY THING PARTY WITHOUT THE NUMBER 0.40mm LEAD THE NUMBER DIMENSIONING & THICKNESS DIMENSION പ THE PIN ΗH AND L SI PN FOR AT T HΗ . ШО Ø *.*--N. m. 4 Ś 6 (inited to the second s 6 NOTES

Figure 6 Package notes, Punched QFN 6x6x0.9mm 36LD 0.5mm Lead Pitch

KNX EIB TP-UART 2+ - IC

5 Tape and Reel Packing



Figure 7 Tape and Reel Packing 1



Technical Manual

pages 43

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Figure 8 Tape and Reel Packing 2

6 Soldering Profile

Symbol	Parameter	Value	Uni	
-			t	Note
T _c	Classification Temperature	260	°C	
T _{smin}	Temperature min	150	°C	Preheat/Soak
T _{smax}	Temperature max	200	°C	Preheat/Soak
ts	Time	60-120	S	T _{smin} to T _{smax}
T_L to T_P	Ramp-up rate (T_L to T_P)	≤ 3	°C/s	
TL	Liquidous Temperature	217	°C	
tL	Time (t_L) maintained above T_L	60-150	S	
Τ _Ρ	Peak package body temperature	260	°C	
t _P	Time (t_P) within 5 °C of the specified classification temperature (T_C) , see Figure 5-1	30	S	
T_P to T_L	Ramp-down rate (T_P to T_L)	≤ 6	°C/s	
t ₂₅ to t _P	Time 25 °C to peak temperature	≤ 8	min	

Table 26 Soldering Profile



Figure 9 Soldering Profile

pages 43

Moisture Sensitivity Level:3Maximum number of running a reflow profile:3Plating:pure tin (matte tin)

7 Appendix

7.1 Typical Application Circuits

In all the applications circuits shown below a default value of VCC=5V is used.

7.1.1 Mode of Operation – Normal



 recommended (close to Pins VDDH and 2. BDS shall not float

Figure 10 Mode of Operation – Normal

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7.1.2 Mode of Operation – Analog

- 3. recommended (close to Pins VDDH and VCC)
- 4. The maximum average power dissipation of the transmitting resistance R1 of 1 W is valid for an active telegram rate of 50 %.
 - Figure 11 Mode of Operation Analog

7.2 Layout Guidelines

The guidelines related to Figure 10 Mode of Operation – Normal.

Nr.	Component	Layout Guidelines	Priority
1	C9	As close as possible to VDP and GND	1
2	C8	As close as possible to VSSH and VDDH	2
3	L1	As close as possible to IND and GND	2
4	C5	As close as possible to VCC and GND	2

5	C3	As close as possible to VCC and GND	3
6	CBYP	As close as possible to BYP and VB+	2
7	C6	As close as possible to VSP and GND	2
8	Y1	As close as possible to X1 and X2 Embed Y1 (crystal) and its connections on the component side in GND Place on next layer below Y1 a GND area.	1
9	TP-UART 2+	Ground plane on component side and below TP-UART 2+ has to be designed. Four vias are necessary.	1

Table 27 Layout Guidelines



Figure 12 Layout Top-/Bottom View

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Figure 13 Layout Topview



Figure 14 Layout Bottom View

pages 43